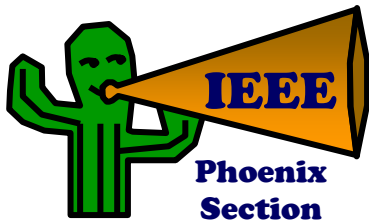


The Valley Megaphone

Newsletter of the
**Institute of Electrical and
Electronics Engineers, Inc.,
Phoenix Section**
August 2014,
Volume XXVIII, Number 8



Executive Committee 2014

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IEEE Phoenix Section on-line updates can be found at <http://sites.ieee.org/phoenix/> and on LinkedIn at: <http://www.linkedin.com/groups?gid=2765918> and on Facebook at: <https://www.facebook.com/IEEEPhoenixSection>

Please send announcements for the *Valley Megaphone* to Mahesh Shah at mkshah@ieee.org for inclusion in the Section Calendar.

All meetings announced in the Phoenix Section Megaphone or on the Phoenix Section Calendar are open to everyone (IEEE members and non-Members)

IEEE Phoenix Section 2014 Annual Banquet pictures are available to view and download at <http://sites.ieee.org/phoenix/2014/03/03/pictures-from-the-2014-annual-banquet/>

Chapters

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Life Members

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Women In Engineering

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Young Professionals

Shafiul "Jacky" Islam 520-245-9010
shafiul.islam@intel.com

U – News

(for Student Members)

Updates of Student Advisors and Committee Members

Each Student Branch noted on the right side of this page should review current information on Advisors and Student Committee Members and forward to my attention within this week, as we are reviewing contacts for reporting and activities including Student Monthly Meetings.

S. Diane Smith
602-749-4601
sdianesmith@computer.org
Student Activities Chair

Start your own MicroMouse and compete for cash prizes!

The Section has a full tournament sized MicroMouse maze. Funding for your project may be available. For details contact the Section Student Activities Chair, S. Diane Smith sdianesmith@computer.org

Student Branches

ASU Main, Engineering

Chair: Jennifer Taggart
928-581-5198,
jennifer.taggart@asu.edu
Advisor: Cihan Tepedelenlioglu,
480-965-6623, cihan@asu.edu

ASU Main, Computer Society

Chair: TBD
Advisor: Guoliang Xue
480-965-6218, xue@asu.edu

ASU Polytechnic

Chair: TBD
Advisor: TBD

DeVry, Phoenix

Chair: Lori Renaldi
lorirenaldi@computer.org
Advisor: Diane Smith
dsmith2@devry.edu

DeVry, Computer Society

Chair: TBD
Advisor: Diane Smith
dsmith2@devry.edu

NAU, Engineering

Chair: TBD
Advisor: Niranjana Venkatraman
v.niranian@ieee.org

Embry-Riddle, Prescott

Chair: Lisa M. Ferguson
FERGUSL2@my.erau.edu
Advisor: John E. Post
posti@erau.edu

U – Newsbytes

ASU Polytechnic is currently seeking Advisor for the Student Branch. Please email Diane (at email address above) with Recommendations.

This month we had a meeting and a presentation about the High altitude balloon experiments done by ASU and ERAU was shown at the monthly meeting. DR Cone and ten other persons attended the banquet in Phoenix. There was a lunch and learn held at the Hazy library (ERAU campus library) about the type of articles and media available for research from the IEEE in our library and how to access it. The group also sponsored a representative from labview to come and demonstrate their product for a large group of people.

Our group did sponsor an "egg drop" contest for campus engineering week. The Idea was to get students involved to design a device in which an egg can survive a drop from a 3 story building. The criteria for the contest was based on the weight, number of pieces of the device, and if the device hit the target. I do have pictures from the event if you would like to see them.

Thank you
Brenda Moerchen
Secretary, ERAU Chapter, Prescott



Upcoming Conferences in August in Region 6

No input for Conferences in Region 6

We are starting to work on plans for a Metro Area Workshop for Phoenix in March of next year (2015). If anyone would like to volunteer, please contact your society local chapter or myself at Phoenix.conferences@ieee.org. If there are suggestions for topics or speakers, please contact the above mentioned officers.

Our goal is to provide solid education (with CEUs) and an opportunity to network and meet fellow engineers, all at an affordable price.

Look forward to seeing you there.

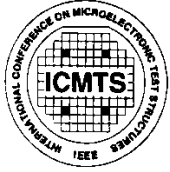
If you have any suggestions for speakers, or if your group is looking to have a conference in Arizona, please contact our new direct email Phoenix.Conferences@ieee.org



Call for Papers

28th International Conference on Microelectronic Test Structures

March 23-26, 2015, Phoenix, Arizona USA



General Chair:

Larg Weiland
PDF Solutions
larg.weiland@pdf.com

Technical Chair:

Colin McAndrew
Freescale Semiconductor, Inc.
Colin.McAndrew@freescale.com

Tutorial Chair:

Brad Smith
Freescale Semiconductor, Inc.
Brad.Smith@Freescale.com

Local Arrangements:

Colin McAndrew
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Colin.McAndrew@freescale.com

Equipment Exhibition:

Bill Verzi
Agilent/Keysight Technologies
bill_verzi@agilent.com

Asian Representative:

Kunihiro Asada
VLSI Design and Education Center
University of Tokyo
asada@silicon.u-tokyo.ac.jp

European Representative:

Anthony Walton
Scottish Microelectronic Centre
University of Edinburgh
Anthony.Walton@ee.ed.ac.uk

USA Representative:

Loren Linholm
linhlw@comcast.net

Conference Manager:

Wendy Walker
Widerkehr and Associates
wwalker@widerkehr.com

The 28th International Conference on Microelectronic Test Structures (ICMTS) will be held in Phoenix, Arizona, USA, bringing together designers and users of test structures to discuss recent developments and future directions. The conference will be held March 24-26, 2015, preceded by a one-day Tutorial Short Course on Microelectronic Test Structures on March 23. There will be an equipment exhibition relating to test structures and measurements. Original papers are solicited presenting new developments in test structures, as well as their implementation, measurement, and application, related to semiconductors, nanotechnology, and MEMS. A Best Paper award will be presented by the Technical Program Committee. The conference is sponsored by the IEEE Electron Devices Society and all published papers will be posted to IEEE Xplore®.

Topics of relevance to ICMTS include, but are not limited to:

Material and Process Characterization: Wafer material evaluation for SiGe, strained Si, Si-on-insulator, Ge, GaAs, GaN and other compounds. Resistivity, mobility, stress, contact resistance, dielectric, and interconnect measurements. Test structures and methods to evaluate new materials and devices, e.g. graphene and CNTs.

Test structure design methods: Flows for automated test structure design, generation, and verification; design-for-analysis, parameterized design, layout issues (grid, hierarchy, misalignment), switched arrays.

Replicated Feature Metrology: Level-to-level registration, overlay, CD uniformity and control, non-electrical characterization techniques, mask and reticle process control.

Manufacturing of Integrated Circuits and MEMS: Evaluation of individual and groups of integrated circuit, device, and MEMS process steps and elements: transistors, diodes, mechanical structures, device isolation, memory cells, and interconnect. Assessment of MMICs and RF components and products. Evaluation and optimization of standard cell macros and other circuits.

Reliability and Product Failure Analysis: Test structures for quality assurance, transistor, thin film, dielectric, and interconnect reliability, thermal monitoring and analysis, accelerated wafer level tests, wafer level burn-in, failure identification, reliability prediction.

Nanotechnology, Displays, and Emerging Devices: Test structures and methods to evaluate nanotechnology (materials and devices), displays, optoelectronic materials and devices, novel memories, and related materials.

(BIO-)MEMS, (BIO-)Sensors, and Actuators: Test structures for MEMS and micromachining including physical/chemical/optical/bio sensors, photonic devices, amorphous silicon films and devices.

Device and Circuit Modeling, Parameter Extraction: Model parameter extraction, RF device modeling, de-embedding, pulsed measurements, DC and high frequency measurement techniques and applications.

Technology R&D, Integration, and DFM: Test structures for FEOL or BEOL evaluation, design rule determination, process uniformity and worst-case analysis, test structures to assess integration and new technologies, switched array test chips/devices for large scale evaluations and reduced pad count.

Test Circuits: Novel on-wafer circuits for characterization of manufacturing technologies, variability, yield, and performance. Circuits to simplify probing, improve measurement robustness, and reduce pad count.

Yield Enhancement, and Production Process Control: Yield enhancement structures and methods, critical area calculation, defect estimation structures and methods, yield modeling, evaluation of design-manufacturing interactions, place and route methodology, and statistical process control. Large-scale, many-component test arrays and multiplexing techniques for technology assessment.

Test Structure Measurement Utilization Strategy: Test equipment, probing and programmable testing for process diagnostics, optimizing test throughput, database and data analysis methods, statistical data analysis, expert systems and related techniques, including capacitance, voltage, current, resistance, optical, and thermal measurements.

Matching and Variability Test Structures: Matching and variability of components (transistors, resistors, capacitors, inductors) and layout for circuit applications and their evaluation. Characterization of identically designed components. Modeling of matching and variability.

Authors are asked to submit an abstract of up to four pages in PDF format (font-embedded). The first page **must** consist of a title, a 50-words summary, author name(s), the full address, fax number, and e-mail address of the lead author, and author preference for oral or poster session presentation, if any. The body of the abstract should be three pages or less consisting of one page of text (800 to 1000 words) and up to two pages containing major figures and tables. Please visit the ICMTS 2015 official web site icmts2015.pdf.com for further information and paper submission. You may care to join the ICMTS group at www.linkedin.com.

The selection process will be based on the technical merit and will be highly weighted in favor of papers that have a high test structure content, include measured data and analysis, together with illustrations of the test structures involved. The submission deadline is **October 17, 2014**. Notice of paper acceptance, with instructions for manuscript preparation for the conference proceedings, will be sent to the authors of the papers selected for presentation by early December, 2014. The deadline for submission of the final paper will be January 20, 2015.

Details of the venue, hotel, registration, etc. will be posted at icmts2015.pdf.com as they are finalized.

For further technical information, please contact the technical chair:

Colin McAndrew, Freescale Semiconductor, Inc., Colin.McAndrew@freescale.com

2014 IEEE Custom Integrated Circuits Conference (CICC '14)

Showcase for Circuit Design in the Heart of Silicon Valley

September 15 –17, 2014, DoubleTree Hotel, San Jose, California

Sponsored by the IEEE Solid-State Circuits Society
Technically co-sponsored by the IEEE Electron Devices Society

***Conference Registration and hotel reservation links are now active.
Registration deadline is September 5. The hotel reservation deadline is August 11.***

Conference Registration: The advance registration deadline for the lower registration fee is September 10. Advance registration closes on September 5. After that date, you need to register onsite at the conference. *Register now and save money.*

Online Registration: To register for the conference online, go to the website – www.ieee-cicc.org, Click on the General Information button on the left side menu, click on Registration for online registration. Follow the directions.

Hotel Reservations: The hotel reservation deadline for the IEEE Custom Integrated Circuits Conference is Monday August 11, 2014. Reservations must be made by that date to qualify for the CICC room rate. The conference will take place at the DoubleTree Hotel, 2050 Gateway Place, San Jose, California. The room rate is \$149 for a single or double room. All rooms must be guaranteed with a credit card. The hotel has an outdoor swimming pool as well as exercise facilities

Online Reservations: To make your hotel reservations online, go to the CICC website at www.ieee-cicc.org. Click on General Information on the left side menu. Click on hotel to make a hotel reservation. Follow the directions to make your reservation.

Reservations by phone: To make your hotel reservations by phone, call the DoubleTree Hotel at 408-453-4000. Tell them you are with IEEE CICC to get the CICC room rate.

Here are some of the highlights of 2014 CICC:

Educational Sessions Program

This year the Educational Sessions are embedded with the technical program.

They are on Monday, Tuesday and Wednesday.

Entrance to the Educational Sessions is included in the registration fee.

Monday & Tuesday, Sept 15 & 16:

- Poster Presentations
- Vendor Exhibit

Monday - Wednesday, September 15-17:

Technical Program

The Technical Program teams are very enthusiastic about the 2014 technical papers by experts from the Industry and Academia. *This year we are continuing the Technical Forum session platform.* In addition, the traditionally popular invited papers, and panel sessions will entertain and inform the audience.



THE INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS, INC.

IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

IEEE Components, Packaging and Manufacturing Technology Society Phoenix Chapter

2014 Executive Committee for CPMT Chapter for IEEE-Phoenix Section

Position	Name	Phone Contact	Email Contact
Chair	Dr. Mahesh K. Shah	(480) 544-9438	mkshah@ieee.org
Asst. Chair	Mr. Vivek Gupta	(480) 734-2366	vmgupta@msn.com
Secretary	Dr. Devarajan Balaraman	(480) 619-0944	iangoinbiking@gmail.com
Treasurer	Dr. Vasudeva P. Atluri	(480) 227-8411	vpatluri@ieee.org
Program Chair	Mr. David Dougherty	(480) 245-8099	david.dougherty@freescale.com
Asst. Program Chair	Dr. Nageswara R. Janapala	(650) 213-6733	nageswara.r.janapala@intel.com
Tutorial Chair	Dr. Ashish Gupta	(480) 554-2409	ashish.x.gupta@intel.com
Asst. Tutorial Chair	Adel Elsherbini	(734) 686-2278	a.elsherbini@gmail.com
Workshop Chair & Publicity	Dr. Vasudeva P. Atluri	(480) 227-8411	vpatluri@ieee.org
Website Co-Chair	Huiyang Fei		Huiyang.H.Fei@ieee.org
Website Co-Chair	Bharat Penmecha	(480) 552 2511	bharat.penmecha@ieee.org

Tentative Schedule for Monthly Seminars

We are working to arrange monthly Seminars on topics of interest to our members. If you have suggestion for topics and/or speakers please contact any of the executive committee members listed above.

August 27 – Dr. Darrel Frear – Packaging Needs for Automotive Radar

September – Dr. Jon Harris – Packaging for LED Lighting

October – Dr. Stuart Bowden – Solar Cells

November – Dr. Jaynal Molla – Plating for Electronic Packaging

Additional Activities –Tutorial and Workshop

Phoenix section is planning to hold a Half Day tutorial on the topic of **Reliability Engineering** in early Fall. In addition we are working with other Society Chapters to hold a workshop on **Emerging Device and Packaging Technology** in late November or Early December. Please wait for announcements in near future



THE INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS, INC.



IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

IEEE Components, Packaging and Manufacturing Technology Society Phoenix Chapter

Wednesday, August 27th, 2014 at 5:30 PM

Radar Devices, Challenges and Packaging Technology Solutions

Dr. Darrel Frear

Freescale Semiconductor

Packaging Technology Development
Tempe, AZ 85284 USA
darrel.frear@freescale.com

ABSTRACT

One of the most important goals in the automotive industry is to make cars safer and have no fatalities. Standard safety equipment includes airbags, electronic steering control, etc. The trend now is to move to Advanced Driver Assistance Systems (ADAS) to help the driver in the driving process. ADAS are systems developed to automate/adapt/enhance vehicle systems for safety and include safety features designed to avoid collisions and accidents by offering technologies that alert the driver to potential and or avoid collisions by implementing safeguards and taking over control of the vehicle. One of the key elements in ADAS is the use of radar in automobiles to alert drivers to potentially dangerous situations and, in many systems, take control of the vehicle faster than a human can react. One of the key challenges in automotive radar is developing a robust packaging solution. This presentation provides an overview of the challenges and requirements of creating a robust package solution for automotive radar applications. A review of advanced safety systems being developed by automakers to meet world-wide regulatory requirements and prompted by customer expectations will be presented, including radar systems. Radar devices will be used for both long range (several hundred meters in front of the driving vehicle) and short range (identification of obstacles close (within 30 meters) to the side or rear of the vehicle. One of the key challenges in packaging radar is the high frequency (77GHz) electrical performance where isolation is critical and loss must be minimized and, at these high frequencies, the package must be treated and designed as part of the electrical circuit. Additional challenges highlighted will include thermal and reliability requirements. To meet these automotive radar package challenges, Freescale has developed a world-class solution packaged radar solution using the Redistributed Chip Package technology that meets electrical and reliability performance requirements. The performance and reliability attributes of this package solution will be discussed with results showing this is a viable robust solution for automotive radar.

BIOGRAPHY

Darrel Frear earned an A.B. in Engineering Science from Dartmouth College (1982) and M.S. (1984) and Ph.D. (1987) degrees in Materials Science from the University of California, Berkeley. He is a Managing Member of the Technical Staff at Freescale Semiconductor and manages Package Development in the Packaging Solutions Division. Previously, Dr. Frear was with Sandia National Labs as a Principle Member of the Technical Staff. His technical focus has been on advanced packaging development including materials, manufacturing and reliability of electronic components.

Date: Wednesday, August 27th, 2014

Location: Group Conference Room, Freescale Semiconductor, Inc., 2100 E. Elliot Rd. Tempe, AZ. There are new signs on the property (Discovery Business Center). Enter the facility through the Main (South) Lobby in building 94 and sign in with Security (*Photo ID required*). You will be escorted to the meeting room.

Agenda: 5:30–6:00 PM: Social/Refreshments, 6:00–7:00 PM: Presentation, 7:00 PM: Dinner
(Pizza and Soda will be provided by the IEEE Phoenix Section CPMT Society Chapter)

IEEE members and non-members are all welcome to attend. Those who plan to attend should be at the facility entrance no later than 5:45 PM, as there will be no escorts available after that.

For more information, please contact any of the following CPMT officers:

Vasu Atluri	(480) 227-8411	Devrajan Balaraman	(480) 619-0944	David Dougherty	(480) 413-6923
Adel Elsherbini	(734) 686-2278	Ashish Gupta	(480) 554-2409	Vivek Gupta	(480) 734-0266



IEEE

IEEE

Signal Processing Society



**IEEE
COMMUNICATIONS
SOCIETY**

SP-COM Phoenix Chapter

Please join our Google Group!

We have recently started a google group to be able to send you more timely announcements via email for upcoming events and talks. Please sign up for timely email announcements at the below link

<https://groups.google.com/d/forum/ieee-sp-com-phoenix-chapter>

We are limiting member permissions only to receiving emails posted by the group owner - the SP-COM chapter chair.

Technical Co-Sponsorship by the IEEE Signal Processing and Communications Chapter, Phoenix Section

We continue to post meeting notices on IEEE vtools at (<https://meetings.vtools.ieee.org/main>)



**IEEE Power and Energy Society
Phoenix Chapter**

<http://www.ewh.ieee.org/soc/pes/phoenix/>



News and Announcements:

- Want to know more about IEEE Power and Energy Society? Watch this video:
 - http://www.youtube.com/watch?v=BRKM4lpo_tk
 - More videos are available at:
<http://ieee-pes.org/outreach/pes-informational-promotional-videos>
- Have you considered becoming a Senior Member of IEEE? It's not as difficult as you think. Basically, you need ten years of professional experience, and your bachelor's degree counts for three of those years. Find out more at:
http://www.ieee.org/membership_services/membership/senior/index.html

57th ANNUAL IEEE-PES FUNDRAISING GOLF TOURNAMENT



NOVEMBER 15, 2014

Be sure to join us at Rio Verde Golf Club, located at 18731 E 4 Peaks Blvd, Rio Verde, AZ 85263, for a 12:45 PM Shotgun Start. The course is located 10 Minutes north of Fountain Hills. (480) 471-9420 <http://www.rioverdecc.com/Map>

This is the annual fundraiser for your IEEE-PES Chapter. The fee is \$100 per player or \$400 to sponsor a foursome. Be sure to come early and stay late as there will be free range balls beforehand and dinner afterwards. Cash prizes awarded for first place, second place, and third to last place teams. There will also be a Raffle, Skills Games, and Giveaways Galore.

Use this sheet to sign up either individually or for your team. You can either:

- **Print out and complete, then mail the form with your payment**
- **Return this form electronically (distribution@gorman-co.com) and then send your payment.**
- **Send payments to: IEEE-PES
c/o Gorman Company
4819 35th Street
Phoenix AZ 85040**

You will be notified via email that your payment has been received and you are registered to participate. If you have any questions, please feel free to call us at (602) 470-0400.

Please provide all requested information, including email addresses for all team members.

TEAM/SPONSOR _____

Player _____ **Dinner?** _____

Email _____

Player _____ **Dinner?** _____

Email _____

Player _____ **Dinner?** _____

Email _____

Player _____ **Dinner?** _____

Email _____

Additional Dinner Guests: _____

To minimize waste and extra costs, we would like your help getting an accurate dinner count.



INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS

WAVES AND DEVICES

PHOENIX CHAPTER

<http://ewh.ieee.org/r6/phoenix/wad/>*2014 Calendar*

<u>Date</u>	<u>Location</u>	<u>Topic / Title</u>	<u>Speaker</u>	<u>Affiliation</u>	<u>IEEE Society</u>
29-Jan	ASU Brickyard	Expanding your knowledge of Laser Fusion and Optical Accelerators	Ken Barat	Consultant	Photonics
6-Mar	ASU Goldwater	Embrace Circuit Nonlinearity to get Transmitter Linearity and Energy Efficiency	Earl McCune	MTT DML	Microwaves
4-Apr	Agilent	Current and Future Trends in Photovoltaics Technologies	Christina Honsburg	ASU	Electron Devices
25-Apr	Freescale	Bio Medical Devices	Jennifer Christen	ASU	Electron Devices
1-May	ASU	Software Defined Radio	Hossein Hashemi	USC	Microwaves/ Electron Devices
22-May	ASU	Antennas	Kathleen L. Melde	UofA	Antennas
Sept	TBD	Device Modeling	Colin McAndrew	Freescale	Microwaves / Electron Devices
Oct	ASU / Freescale	Software Defined Radio	Jeffrey Pawlan	MTT DML	Microwaves
Nov	TBD	Microwave Board Materials	John Coonrod	Rogers Corp	Microwaves
Dec	ASU	Antenna System	Ron Lavin	Boeing Corp.	Antennas



**Technical & Administrative
Meeting October 14, 2014**

Program Presentation: TBD

Meeting Agenda:

TBD

Where: SRP's **PERA Club** Bighorn Room,
1 East Continental Drive, Tempe, AZ
Continental is West of 68th St., ½ mile south of McDowell Road
Enter the Private PERA Club and follow drive to large parking lot. Big Horn Room is the most South east building off parking.

When: Tuesday, October 14, 2014, 11:00am – 1:00pm, Registration fee is \$15. This fee will include lunch provided by the PERA Club. Lunch will be: to be voted on

RSVP:

The Program Chair is seeking suggestion from members for future presentations. Any ideas of interest to LM are open for consideration. Please contact Ronald Sprague Program Chair at r.sprague@ieee.org or any officer with ideas.

About IEEE Phoenix Section Life Member Affinity Group:

The IEEE Phoenix Section Life Member Affinity Group was organized to enable IEEE Life Members to retain active IEEE associations, contribute to the social good in their communities, advance IEEE's professional interests and enjoy each other's company.

Activities: Technical meetings scheduled in February, May, October, and December. Elections are held at the December meeting.

Future Technical Meetings: All meeting are scheduled at the SRP PERA CLUB. It is suggested you put these dates on your calendar to attend our meetings.

- Tuesday, October 14, 2014
- Tuesday, December 9, 2014

Officers:

Chair	Leslie Daviet II	lesdavietii@cs.com
Vice Chair	Position is Vacant	
Secretary	Tom Lundquist	Tom.Lundquist@ieee.org
Treasurer	Leslie Daviet II	lesdavietii@cs.com
Program	Ronald L. Sprague,	r.sprague@ieee.org
Past Chair	A. Barry Cummings	abarrycummings@gmail.com



IEEE Young Professionals (formerly GOLD) Phoenix Section Executive Board

- Chairman: Shafiul “Jacky” Islam (shafiul.islam@intel.com)
- Vice Chair: Jennifer Taggart (jennifer.taggart@asu.edu)
- Secretary/Webmaster: Joseph Caglio (joseph.m.caglio@intel.com)
- Treasurer: Ashley Meredith (ashley.meredith@aps.com)

June 20, 2014, IEEE Phoenix Young Professionals Movie Night

We had a movie night on June 20th at 7:40pm at Harkins Theater Arizona Mills, 5000 Arizona Mills Cir. Tempe, AZ 85282.

There were about 12 attendees who had the chance to mingle with fellow young professionals. Unfortunately, “Edge of Tomorrow” was not showing at that time and as a group, we voted to watch “Godzilla” as an alternative.

Organizer: Ashley Meredith (ashley.meredith@aps.com)

June 29, 2014, Officers’ Meeting

All of the four officers attended an officers’ meeting on June 29 from 7:00pm to 9:00pm over Google Hangouts to discuss our event plan and budget for Fall. We are expecting to have a Career Mixer, Speaker Series, Social events, and a Virtual Leadership Conference. We also discussed about sending out surveys, website, collaboration tools, social media, and Polo / T-Shirts. We will be providing more details as we finalize and implement our plans.

Organizer: Shafiul “Jacky” Islam (shafiul.islam@intel.com)

July 4, 2014, Independence Day (United States) Celebration

Come celebrate the 4th of July at the Tempe Beach Park party with IEEE Young Professionals Phoenix Section. Enjoy music and food from various vendors. Tickets can be bought early for \$5 at all Fry's Food Stores until July 3rd. Tickets can also be bought at the gate for \$8. We will meet at the main entrance at 7pm. More information can be found at <http://www.tempe4th.com/index.asp> with locations for parking spots and road closures. Friends and family are welcome to attend! Hope to see you there!

Please take a moment to register (so that we have a roster of attendees) at:

https://meetings.vtools.ieee.org/meeting_view/list_meeting/27045

Please contact Joseph Caglio (joseph.m.caglio@intel.com) with questions.

July 31, 2014, Officers’ Meeting

All of the four officers attended an officers’ meeting on July 31 from 7:00pm to 8:00pm over Google Hangouts for team synchronization and discussion on topics from our previous officers’ meeting. We also discussed our succession plan effective January 2015.

Organizer: Shafiul “Jacky” Islam (shafiul.islam@intel.com)

Upcoming Events

To be announced.



2014 IEEE Phoenix Section News

Executive Committee Meeting

No meeting of Executive Committee in July & August

Normal meetings are on first Tuesday of the month from 6:00 PM to 8:00 PM
The Airport Hilton Phoenix,
2435 S 47th St. Phoenix, AZ 85034, (480) 894-1600.

2014 Executive Committee

Chair: Barbara McMinn
Vice Chair: Bruce Ladewig
Secretary: Surinder Tuli
Treasurer: Vivek Gupta
Past Chair: Charles Weitzel

Executive Committee Meetings

Date: First Tuesday of every month, except July and August

Time: 6:00 – 8:00 p.m.

Location: Hilton Phoenix Airport, 2435 South 47th Street, Phoenix, AZ 85034

IEEE Phoenix Section Annual Banquet 2014 Photos are Posted at:

<http://sites.ieee.org/phoenix/2014/03/03/pictures-from-the-2014-annual-banquet/>

IEEE Phoenix Section – Forming Reliability Chapter

Reliability Chapter Forming

The IEEE Reliability Society (IEEE RS) plans to collaborate with the IEEE Phoenix Section, as well as, the IEEE Sections in Tucson and Sierra Vista/Ft Huachuca in forming this new state-wide IEEE Reliability Chapter. The Reliability Chapter will focus on 3 meetings in the first 6 months after being created. The topics that may be discussed will include new IEEE Reliability Standards (e.g., IEEE 1633), new software reliability techniques and reliability growth techniques. The IEEE RS plans to rotate Chapter meetings between the 3 state locations. If you are a member of the IEEE, but not an IEEE-RS member, you could join the society for \$35 and be a charter member to help in the formation of this new Chapter. If you are an IEEE RS member or interested in Reliability Society, please contact Lou Gullo at Louis.Gullo@ieee.org.

IEEE Senior Member and Fellow Grade

IEEE Phoenix Section Membership Development would like to nominate eligible IEEE Members from the Section to Senior Member and Fellow Grades. Please review the requirements at www.ieee.org for eligibility.

Eligible candidates are requested to send in their resumes to Dr. Vasudeva P. Atluri, Membership Development Coordinator, at vpatluri@ieee.org and Dr. Charles E. Weitzel, Section Chair, at c.weitzel@ieee.org for consideration.

Phoenix Section LinkedIn Group


If you are interested in professional networking and shared Section related updates & discussions join the [IEEE Phoenix Section Group on LinkedIn](#). Signing up only takes minutes and is free. A job board is available as well.

You can also go to IEEE Phoenix Section LinkedIn page by clicking  button on the [IEEE Phoenix Section home page](#)

IEEE Phoenix Section Ventures into Social Media

You can access the web page three ways:

Use the URL: <https://www.facebook.com/IEEEPhoenixSection>

Click on the Facebook logo  link from [IEEE Phoenix section home page](#).

Search for IEEE Phoenix Section from your Facebook page.

We need following help.

1. Each of you access the IEEE Phoenix Section Web page and click on "Like" hyperlink.
2. Go on the Friends section of the page and "Invite Your Friends." Once you click on Invite button, it will get your email contact list. Your facebook contact list will already be populated with your Facebook friends and you can simply click the Invite button next to their name. Please invite as many friends as you can.
3. Provide me the contents for posting on a regular basis - meeting/ event announcements, Event pictures, Videos.
4. Start some discussion topics under - Status section.

IEEE Membership Grade Advancement

IEEE Phoenix Section Executive Committee encourages all to apply for advancement in membership grade to Senior Member and Fellow Grade. Please review the requirements at www.ieee.org. Please contact IEEE Phoenix Section Membership Development Chair, Dr. Vasudeva P. Atluri, at vpatluri@ieee.org for additional information.

Enhanced Senior Member Application Launched

Effective 29 July 2011, IEEE Admission and Advancement launched a [new Senior Member Application](#). The new application includes numerous enhancements, based on feedback from volunteers and members, including:

- New user friendly format / design
- Secure environment (need IEEE Web account)
- Ability to save application in “draft” form
- Ability to upload resume or Curriculum Vitae (up to 3 MB)
- Applicant can view application online
- Applicant can view status of requested reference forms
- References will be notified by email to provide applicant reference
- References will have the ability to view their completed reference form(s)
- Real time application status

The goal is to provide prospective Senior Members with an easy to use and intuitive interface, while streamlining internal operations at the same time. [View the new Senior Member application](#).

IEEE Member's Benefits

IEEE-USA Offering Survivor Planning E-book Free to IEEE Members

August Free E-Book

In August, IEEE-USA is offering “Survivor Planning: What Every Spouse Should Know” free to IEEE members.

In this practical reference, the late George F. McClure urges readers “not to leave your family in the dark, digging to find important documents and information. Life has to go on after a spouse, partner or parent passes away. Dealing with the myriad of decision processes immediately following a death in the family is a confusing ordeal.”

“Survivor Planning” has a checklist to help you organize all the important information you will need, and Websites where you can find additional help. It also provides guidance in advance planning, retirement benefits, wills, living trusts and finances.

McClure shares that having these discussions and making decisions with your family about life’s everyday matters will not lessen your grief, but it will help your family avoid some anxiety, stress and frustration when you are gone.

“Survivor Planning: What Every Spouse Should Know” can be downloaded at <http://www.ieeeusa.org/communications/ebooks/files/aug14/m28932i/Survivor-Planning-What-Every-Spouse-Should-Know-2010-Update.pdf> for free to IEEE members. \$5.99 for non-members.

To purchase IEEE member-only products, and to receive the member discount on eligible products, you must log in with your IEEE Web account.

Call for Authors

IEEE-USA E-books seek authors to write an e-book, or an e-book series, on career guidance and development topics. If you have an e-book idea that will benefit members on a particular topic of expertise, email your proposal to IEEE-USA Publishing Manager Georgia C. Stelluto at g.stelluto@ieee.org and IEEE-USA Communications Committee Chair Gus Gaynor at g.gaynor@ieee.org.

IEEE-USA serves the public good and promotes the careers and public policy interests of more than 200,000 engineering, computing and technology professionals who are U.S. members of IEEE.

Web: www.ieeeusa.org

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Join IEEE: www.ieee.org/join

Contact: Sharon C. Richardson, Coordinator
IEEE-USA Communications & Publishing
Phone: 1 202 530 8363
E-mail: s.richardson@ieee.org

IEEE-USA Seeks to Honor U.S. IEEE Members, Journalists, Public Officials for Service & Achievements; Nominations Due 29 August

IEEE-USA is seeking nominations to recognize outstanding service and achievements of U.S. IEEE members, journalists and public officials.

IEEE-USA awards are presented in recognition of professional, technical, entrepreneurial and literary contributions to public awareness and understanding of engineering in the United States. 2014 award recipients will be honored during the 2015 IEEE-USA Annual Meeting in Milwaukee. The nomination deadline is 29 August.

Nominations are sought to honor members in the following areas:

- * Robert S. Walleigh Distinguished Contributions to Engineering Professionalism Award
- * George F. McClure Citation of Honor
- * K-12 STEM Literacy Committee Educator-Engineer Partnership Award

- * IEEE-USA Entrepreneur Achievement Award for Leadership in Entrepreneurial Spirit
- * IEEE-USA Jim Watson Student Professional Awareness Achievement Award
- * Regional/Divisional Professional Leadership Award
- * Professional Achievement Award (for individuals and organizations)
- * Harry Diamond Memorial Award
- * Electrotechnology Transfer Award

The following awards are not limited to IEEE members:

- * Award for Distinguished Literary Contributions Furthering Public Understanding and the Advancement of the Engineering Profession
- * Award for Distinguished Public Service

For more information and a description of each award, see <http://www.ieeeusa.org/volunteers/awards/index.html>, or contact David Iams at d.iams@ieee.org.

Nomination forms are available at <http://www.ieeeusa.org/volunteers/awards/forms.html>.

IEEE-USA's Highest Honor

The Robert S. Walleigh Distinguished Contributions to Engineering Professionalism Award is the highest honor IEEE-USA bestows. It is designed to recognize U.S. IEEE members for “long-term dedicated effort and outstanding accomplishments in advancing the aims of IEEE professional activities in the United States.”

Lennart E. Long, a co-founder and former chair of the IEEE International Symposium on Technologies for Homeland Security, won the 2013 Robert S. Walleigh Award. This event began the spring after the tragedy of 9/11 and showcases homeland security technologies capable of deployment within five years.

Walleigh was an IEEE member electrical engineer who worked for the National Bureau of Standards – now the National Institute of Standards and Technology (NIST) – for more than 35 years. After retiring as a senior adviser for international affairs in 1979, he worked 18 years as a senior specialist for IEEE-USA.

To read more about Long and all the 2013 IEEE-USA award winners, see <http://www.ieeeusa.org/communications/releases/2014/071114.asp>.

IEEE-USA serves the public good and promotes the careers and public policy interests of more than 200,000 engineering, computing and technology professionals who are U.S. members of IEEE.

Web: www.ieeeusa.org

Facebook: www.facebook.com/ieeeusa

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Benefits of IEEE membership: www.ieee.org/join

Contact: Chris McManes
IEEE-USA Public Relations Manager
202-530-8356
c.mcmanes@ieee.org

GoogleApps@IEEE Now Available to IEEE Members

GoogleApps@IEEE is a suite of products offered to IEEE members to enhance peer-to-peer communications and collaboration. The suite of applications includes e-mail, calendaring, contacts, and document sharing along with other collaborative tools. 30G of available cloud storage memory is available for these applications. Learn more about <http://www.ieee.org/googleapps>

GoogleApps@IEEE is available to members at no additional cost, bringing access to:

- A unique IEEE e-mail address (e.g., John.A.Doe@ieee.org);
- Mail forwarding or e-mail inbox (Gmail);
- 30-gigabytes of shared storage (Gmail and Google Drive);
- 99.9 percent up time guaranteed by Google;
- Advertisement-free Gmail;
- Files stored in the cloud for easy sharing and access from anywhere via Google Drive.